Very Large Scale Disintegration

Adrian Sampson Cornell & Google

computing's carbon footprint

Ecovisor: A Virtual Energy System for Carbon-Efficient Applications

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ABSTRACT

Cloud platforms' rapid growth is raising significant concerns about their carbon emissions. To reduce carbon emissions, future cloud

reliance on renewabl

for Carbon-Eff tional Conferend Operating Syster BC, Canada. ACN

Manufacturing electronic devices is an energy-intensive proce 1 INTRODUCTION For devices with lower utilization, such as consumer-class ele UC San Diego La Jolla, CA, USA tronics or over-provisioned servers, manufacturing dominates lifetime carbon footprint [17]. This is especially true in devices w 1.5 billion smartphones are sold annually, and most are decommisshort use cycles. In the United States alone, 150 million smartphc sioned less than two years later. Most of these unwanted smartare discarded each year, amounting to one phone discarded per phones are neither discarded nor recycled but languish in junk son every two years [8]. As a result, manufacturing account drawers and storage units. This computational stockpile repre-70 – 85% of the lifetime carbon footprint of a smartphone [17 sents a substantial wasted potential: modern smartphones have Consumer electronics are also becoming increasingly powe increasingly performant and energy-efficient processors, extenthe performance of recent smartphones rivals or exceeds that sive networking capabilities, and reliable built-in power supplies. Intel Core-i3 processor (Figure 1). Yet, phones are often disc This project studies the ability to repurpose these unwanted smartdespite being completely (or partially) operational. Otherwis phones as "junkyard computers." Junkyard computers grow global tional electronic devices are retired prematurely due to ter compute capacity by extending device lifetimes, and save carbon by supplanting the manufacture of new devices. We show that style, or planned obsolescence [33]. Compare this to othe priced devices with entire ecosystems of functional obsol the capabilities of even decade-old smartphones are within those demanded by modern cloud microservices, and discuss how to come.g., cars, which are resold until they are "driven into the bine phones to perform increasingly complex tasks. We describe Of course, the performance of computing devices imprort operation-focused metrics do not capture the actual Subarthan that of a modern automobile. What should th Idross this we propose Computa-

Carbon Explorer: A Holistic Framework for Designing Carbon Aware Datacenters

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companies reduce their datacenters' carbon footprint g in renewable energy generation and receiving credits purchase agreements. Annually, datacenters offset their umption with generation credits (Net Zero). But hourly, often consume carbon-intensive energy from the grid n-free energy is scarce. Relying on intermittent renewn every hour (24/7) requires a mix of renewable energy

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1 INTRODUCTION

Carbon-free energy is essential f

Carbon footprint papers at ASPLOS 2023

Junkyard Computing: Repurposing Discarded Smartphones to

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Facebook's datacenter carbon footprint over time



Figure from Chasing Carbon, Gupta, Kim, Lee, Tse, Lee, Wei, Brooks, and Wu; HPCA 2021

"scope 3" is the supply chain, 49% of which is construction & hardware manufacturing

scope 2 without buying renewable energy

"scope 2" is the datacenter power, the energy it takes to run the machines



the chiplet revolution



Apple M1 Ultra 2 dies

Ryzen Threadripper PRO 5995WX 9 dies

Multi-chip modules are suddenly everywhere

Intel Ponte Vecchio GPU 47 dies



64 Arm Neoverse V2 cores



AWS Graviton3 Multi-Chip Module (2022)



DDR SDRAM standards tend to last for a good long while





Design reuse: the fantasy view



Design reuse: in the real world

the chiplet revolution

computing's carbon footprint

silicon recycling





Embedded Device



Next Year's Server





Disintegrate

silicon recycling



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2



Manufacture





Disintegrate





multi-chip module

chiplets

Chiplet disintegration



multi-chip module

Make computers cheaper

Reduce computing's embodied carbon footprint, thereby helping address the most urgent problem that humanity will grapple with in any of our lifetimes

Publish more ASPLOS papers

Reasons to be excited about silicon recycling





1: Carbon-aware architectural disaggregation

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1: Carbon-aware architectural disaggregation

2: Design tools for spare-parts synthesis

classic EDA toolchain

New Hardware, From Scratch

2: Design tools for spare-parts synthesis

chiplets we already have or can get cheaply

a physically reconfigurable FPGA

a physically reconfigurable FPGA

| CLB | CLB | BRAM | |
|-----|-----|------|--|
| | | | |
| CLB | CLB | BRAM | |
| CLB | CLB | BRAM | |
| | | | |

3: Physically reconfigurable fabrics

a physically reconfigurable FPGA

a physically reconfigurable FPGA

| DSP | | DSP | | DSP | | DSP | |
|-----|------|-----|-----|-----|----|-----|---|
| DSP | | DSP | | DSP | | DSP | |
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| CLB | | | CLB | | С | CLB | |
| | BRAM | | | | BF | RAN | 1 |

3: Physically reconfigurable fabrics

a physically reconfigurable FPGA

Disintegrate

silicon recycling

2

Manufacture

amazing ASPLOS research reveals the incredible system-level potential of silicon recycling

silicon recycling seems cool and could help address computation's carbon cost

chiplet disintegration is not realistic

amazing ASPLOS research reveals the incredible system-level potential of silicon recycling

silicon recycling seems cool and could help address computation's carbon cost incentive drives innovation in silicon recycling technology

chiplet disintegration is pot realistic

